

ABSTRACT

Provided is a method for producing an anisotropic conductive sheet that can be used for an inspection of a semiconductor package or a high-frequency component part, in which the pitch of wiring is narrowed and the wiring itself has been subjected to wire thinning, and that can be easily produced.

Disclosed is a method for producing an anisotropic conductive sheet, the method including a molding step of molding a conductive filler material-containing composition including (A) a conductive filler material dispersed in an organic solvent and (B) a binder resin, into a sheet-like body, and an organic solvent volatilization step of heating one surface of the sheet-like body and thereby volatilizing the organic solvent through the other surface of the sheet-like body.

FIG. 1